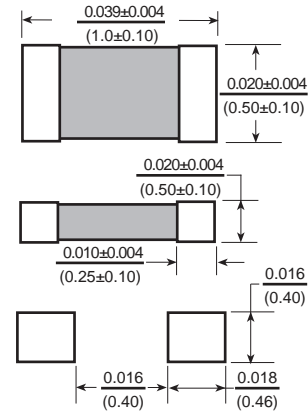


## Multilayer Ferrite Beads

## MLB03



Dimensions:  $\frac{\text{Inches}}{\text{(mm)}}$



Allied Part Number	Impedance ( $\Omega$ ) @ 100 MHz +/- 25%	DC Resistance ( $\Omega$ ) Max.	*Rated Current (mA)
MLB03-060-RC	6	0.05	500
MLB03-100-RC	10	0.05	500
MLB03-300-RC	30	0.30	300
MLB03-330-RC	33	0.30	300
MLB03-400-RC	40	0.30	300
MLB03-470-RC	47	0.40	300
MLB03-600-RC	60	0.40	300
MLB03-700-RC	70	0.40	300
MLB03-750-RC	75	0.40	300
MLB03-800-RC	80	0.40	300
MLB03-900-RC	90	0.50	300
MLB03-101-RC	100	0.50	300
MLB03-121-RC	120	0.50	300
MLB03-151-RC	150	0.50	300
MLB03-221-RC	220	0.50	300
MLB03-241-RC	240	0.50	300
MLB03-301-RC	300	0.80	300
MLB03-331-RC	330	0.80	300
MLB03-481-RC	480	0.80	300
MLB03-601-RC	600	1.00	300
MLB03-102-RC	1000	1.50	100
MLB03-152-RC	1500	2.00	60

\*Temperature rise  $\Delta T = 30^\circ\text{C}$  at rated current.  
All specifications subject to change without notice.

### Features

- Surface mount EMI suppression components
- Nickel barrier termination for excellent resistance to solder heat
- Multi layer technology
- Flow and reflow soldering

### Electrical

**Impedance Range:** 6 $\Omega$  to 1500 $\Omega$

**Tolerance:** 25% over entire range

**Operating Range:**  $-55^\circ\text{C}$  ~  $+125^\circ\text{C}$

**Storage Temp:** Under  $25^\circ\text{C}$  at 40~60% Humidity

**Rated Current:** Based on temp rise not to exceed  $30^\circ\text{C}$

### Resistance to Solder Heat

Pre-Heat  $150^\circ\text{C}$ , 1 minute

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp:  $260 \pm 5^\circ\text{C}$  for 10sec  $\pm 1$  sec.

Minimum of 75% of Electrode covered with new solder.

Impedance within 30% of initial value.

### Test Equipment

(Z): HP4291A RF Impedance/Material Analyzer

(RDC): Chen Hwa 502BC

### Physical

**Packaging:** 10000 per 7 inch reel.

**Marking:** None